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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	13940
Number of Logic Elements/Cells	348500
Total RAM Bits	21270528
Number of I/O	734
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2agz350hf40i4n

Recommended Operating Conditions

This section lists the functional operation limits for AC and DC parameters for Arria II GX and GZ devices. All supplies are required to monotonically reach their full-rail values without plateaus within t_{RAMP}.

Table 1–5 lists the recommended operating conditions for Arria II GX devices.

Table 1–5. Recommended Operating Conditions for Arria II GX Devices *(Note 1)* (Part 1 of 2)

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
V_{CC}	Supplies power to the core, periphery, I/O registers, PCIe HIP block, and transceiver PCS	—	0.87	0.90	0.93	V
V_{CCCB}	Supplies power to the configuration RAM bits	—	1.425	1.50	1.575	V
V_{CCBAT} *(2)*	Battery back-up power supply for design security volatile key registers	—	1.2	—	3.3	V
V_{CCPD} *(3)*	Supplies power to the I/O pre-drivers, differential input buffers, and MSEL circuitry	—	3.135	3.3	3.465	V
		—	2.85	3.0	3.15	V
		—	2.375	2.5	2.625	V
V_{CCIO}	Supplies power to the I/O banks *(4)*	—	3.135	3.3	3.465	V
		—	2.85	3.0	3.15	V
		—	2.375	2.5	2.625	V
		—	1.71	1.8	1.89	V
		—	1.425	1.5	1.575	V
		—	1.14	1.2	1.26	V
V_{CCD_PLL}	Supplies power to the digital portions of the PLL	—	0.87	0.90	0.93	V
V_{CCA_PLL}	Supplies power to the analog portions of the PLL and device-wide power management circuitry	—	2.375	2.5	2.625	V
V_I	DC Input voltage	—	–0.5	—	3.6	V
V_O	Output voltage	—	0	—	V_{CCIO}	V
V_{CCA}	Supplies power to the transceiver PMA regulator	—	2.375	2.5	2.625	V
V_{CCL_GXB}	Supplies power to the transceiver PMA TX, PMA RX, and clocking	—	1.045	1.1	1.155	V
V_{CCH_GXB}	Supplies power to the transceiver PMA output (TX) buffer	—	1.425	1.5	1.575	V
T_J	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	–40	—	100	°C

I/O Pin Leakage Current

Table 1–7 lists the Arria II GX I/O pin leakage current specifications.

Table 1–7. I/O Pin Leakage Current for Arria II GX Devices

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	V_I = 0 V to $V_{CCIOMAX}$	–10	—	10	µA
I_{OZ}	Tri-stated I/O pin	V_O = 0 V to $V_{CCIOMAX}$	–10	—	10	µA

Table 1–8 lists the Arria II GZ I/O pin leakage current specifications.

Table 1–8. I/O Pin Leakage Current for Arria II GZ Devices

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	V_I = 0 V to $V_{CCIOMAX}$	–20	—	20	µA
I_{OZ}	Tri-stated I/O pin	V_O = 0 V to $V_{CCIOMAX}$	–20	—	20	µA

Bus Hold

Bus hold retains the last valid logic state after the source driving it either enters the high impedance state or is removed. Each I/O pin has an option to enable bus hold in user mode. Bus hold is always disabled in configuration mode.

Table 1–9 lists bus hold specifications for Arria II GX devices.

Table 1–9. Bus Hold Parameters for Arria II GX Devices *(Note 1)*

Parameter	Symbol	Cond.	V_{CCIO} (V)												Unit
			1.2		1.5		1.8		2.5		3.0		3.3		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus-hold low, sustaining current	I_{SUSL}	$V_{IN} > V_{IL}$ (max.)	8	—	12	—	30	—	50	—	70	—	70	—	µA
Bus-hold high, sustaining current	I_{SUSH}	$V_{IN} < V_{IL}$ (min.)	–8	—	–12	—	–30	—	–50	—	–70	—	–70	—	µA
Bus-hold low, overdrive current	I_{ODL}	0 V < V_{IN} < V_{CCIO}	—	125	—	175	—	200	—	300	—	500	—	500	µA
Bus-hold high, overdrive current	I_{ODH}	0 V < V_{IN} < V_{CCIO}	—	–125	—	–175	—	–200	—	–300	—	–500	—	–500	µA
Bus-hold trip point	V_{TRIP}	—	0.3	0.9	0.375	1.125	0.68	1.07	0.7	1.7	0.8	2	0.8	2	V

Note to Table 1–9:

(1) The bus-hold trip points are based on calculated input voltages from the JEDEC standard.

Table 1–10 lists the bus hold specifications for Arria II GZ devices.

Table 1–10. Bus Hold Parameters for Arria II GZ Devices

Parameter	Symbol	Cond.	V_{CCIO} (V)										Unit
			1.2		1.5		1.8		2.5		3.0		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus-hold Low sustaining current	I_{SUSL}	$V_{IN} > V_{IL}$ (max.)	22.5	—	25.0	—	30.0	—	50.0	—	70.0	—	µA
Bus-hold High sustaining current	I_{SUSH}	$V_{IN} < V_{IH}$ (min.)	-22.5	—	-25.0	—	-30.0	—	-50.0	—	-70.0	—	µA
Bus-hold Low overdrive current	I_{ODL}	$0V < V_{IN} < V_{CCIO}$	—	120	—	160	—	200	—	300	—	500	µA
Bus-hold High overdrive current	I_{ODH}	$0V < V_{IN} < V_{CCIO}$	—	-120	—	-160	—	-200	—	-300	—	-500	µA
Bus-hold trip point	V_{TRIP}	—	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

OCT Specifications

Table 1–11 lists the Arria II GX device and differential OCT with and without calibration accuracy.

Table 1–11. OCT With and Without Calibration Specification for Arria II GX Device I/Os *(Note 1)* (Part 1 of 2)

Symbol	Description	Conditions (V)	Calibration Accuracy		Unit
			Commercial	Industrial	
25-Ω R_S 3.0, 2.5	25-Ω series OCT without calibration	V_{CCIO} = 3.0, 2.5	± 30	± 40	%
50-Ω R_S 3.0, 2.5	50-Ω series OCT without calibration	V_{CCIO} = 3.0, 2.5	± 30	± 40	%
25-Ω R_S 1.8	25-Ω series OCT without calibration	V_{CCIO} = 1.8	± 40	± 50	%
50-Ω R_S 1.8	50-Ω series OCT without calibration	V_{CCIO} = 1.8	± 40	± 50	%
25-Ω R_S 1.5, 1.2	25-Ω series OCT without calibration	V_{CCIO} = 1.5, 1.2	± 50	± 50	%
50-Ω R_S 1.5, 1.2	50-Ω series OCT without calibration	V_{CCIO} = 1.5, 1.2	± 50	± 50	%
25-Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2	25-Ω series OCT with calibration	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	± 10	± 10	%

The calibration accuracy for calibrated series and parallel OCTs are applicable at the moment of calibration. When process, voltage, and temperature (PVT) conditions change after calibration, the tolerance may change.

Table 1–13 lists the Arria II GZ OCT without calibration resistance tolerance to PVT changes.

Table 1–13. OCT Without Calibration Resistance Tolerance Specifications for Arria II GZ Devices

Symbol	Description	Conditions (V)	Resistance Tolerance		Unit
			C3,I3	C4,I4	
25-Ω R_S 3.0 and 2.5	25-Ω internal series OCT without calibration	V_{CCIO} = 3.0, 2.5	± 40	± 40	%
25-Ω R_S 1.8 and 1.5	25-Ω internal series OCT without calibration	V_{CCIO} = 1.8, 1.5	± 40	± 40	%
25-Ω R_S 1.2	25-Ω internal series OCT without calibration	V_{CCIO} = 1.2	± 50	± 50	%
50-Ω R_S 3.0 and 2.5	50-Ω internal series OCT without calibration	V_{CCIO} = 3.0, 2.5	± 40	± 40	%
50-Ω R_S 1.8 and 1.5	50-Ω internal series OCT without calibration	V_{CCIO} = 1.8, 1.5	± 40	± 40	%
50-Ω R_S 1.2	50-Ω internal series OCT without calibration	V_{CCIO} = 1.2	± 50	± 50	%
100-Ω R_D 2.5	100-Ω internal differential OCT	V_{CCIO} = 2.5	± 25	± 25	%

OCT calibration is automatically performed at power up for OCT-enabled I/Os. When voltage and temperature conditions change after calibration, the resistance may change. Use Equation 1–1 and Table 1–14 to determine the OCT variation when voltage and temperature vary after power-up calibration for Arria II GX and GZ devices.

Equation 1–1. OCT Variation ***(Note 1)***

$$R_{OCT} = R_{SCAL}\left(1 + \langle\frac{dR}{dT} \times \Delta T\rangle \pm \langle\frac{dR}{dV} \times \Delta V\rangle\right)$$

Notes to Equation 1–1:

(1) R_{OCT} value calculated from Equation 1–1shows the range of OCT resistance with the variation of temperature and V_{CCIO}.

I/O Standard Specifications

Table 1–22 through Table 1–35 list input voltage (V_{IH} and V_{IL}), output voltage (V_{OH} and V_{OL}), and current drive characteristics (I_{OH} and I_{OL}) for various I/O standards supported by the Arria II device family. They also show the Arria II device family I/O standard specifications. V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL}, respectively.

For an explanation of terms used in Table 1–22 through Table 1–35, refer to "Glossary" on page 1–74.

Table 1–22 lists the single-ended I/O standards for Arria II GX devices.

Table 1–22. Single-Ended I/O Standards for Arria II GX Devices

I/O Standard	V_{CCIO} (V)			V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
3.3 V LVTTL	3.135	3.3	3.465	–0.3	0.8	1.7	3.6	0.45	2.4	4	–4
3.3 V LVCMOS	3.135	3.3	3.465	–0.3	0.8	1.7	3.6	0.2	V_{CCIO} -0.2	2	–2
3.0 V LVTTL	2.85	3	3.15	–0.3	0.8	1.7	V_{CCIO} + 0.3	0.45	2.4	4	–4
3.0 V LVCMOS	2.85	3	3.15	–0.3	0.8	1.7	V_{CCIO} + 0.3	0.2	V_{CCIO} - 0.2	0.1	–0.1
2.5 V LVCMOS	2.375	2.5	2.625	–0.3	0.7	1.7	V_{CCIO} + 0.3	0.4	2	1	–1
1.8 V LVCMOS	1.71	1.8	1.89	–0.3	0.35 × V_{CCIO}	0.65 × V_{CCIO}	V_{CCIO} + 0.3	0.45	V_{CCIO} - 0.45	2	–2
1.5 V LVCMOS	1.425	1.5	1.575	–0.3	0.35 × V_{CCIO}	0.65 × V_{CCIO}	V_{CCIO} + 0.3	0.25 × V_{CCIO}	0.75 × V_{CCIO}	2	–2
1.2 V LVCMOS	1.14	1.2	1.26	–0.3	0.35 × V_{CCIO}	0.65 × V_{CCIO}	V_{CCIO} + 0.3	0.25 × V_{CCIO}	0.75 × V_{CCIO}	2	–2
3.0-V PCI	2.85	3	3.15	—	0.3 × V_{CCIO}	0.5 × V_{CCIO}	V_{CCIO} + 0.3	0.1 × V_{CCIO}	0.9 × V_{CCIO}	1.5	–0.5
3.0-V PCI-X	2.85	3	3.15	—	0.35 × V_{CCIO}	0.5 × V_{CCIO}	V_{CCIO} + 0.3	0.1 × V_{CCIO}	0.9 × V_{CCIO}	1.5	–0.5

Table 1–23 lists the single-ended I/O standards for Arria II GZ devices.

Table 1–23. Single-Ended I/O Standards for Arria II GZ Devices (Part 1 of 2)

I/O Standard	V_{CCIO} (V)			V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	V_{CCIO} - 0.2	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	0.35 × V_{CCIO}	0.65 × V_{CCIO}	V_{CCIO} + 0.3	0.45	V_{CCIO} - 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	0.35 × V_{CCIO}	0.65 × V_{CCIO}	V_{CCIO} + 0.3	0.25 × V_{CCIO}	0.75 × V_{CCIO}	2	-2

Table 1–23. Single-Ended I/O Standards for Arria II GZ Devices (Part 2 of 2)

I/O Standard	V_{CCIO} (V)			V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
1.2 V	1.14	1.2	1.26	-0.3	0.35 × V_{CCIO}	0.65 × V_{CCIO}	V_{CCIO} + 0.3	0.25 × V_{CCIO}	0.75 × V_{CCIO}	2	-2
3.0-V PCI	2.85	3	3.15	—	0.3 × V_{CCIO}	0.5 × V_{CCIO}	3.6	0.1 × V_{CCIO}	0.9 × V_{CCIO}	1.5	-0.5
3.0-V PCI-X	2.85	3	3.15	—	0.35 × V_{CCIO}	0.5 × V_{CCIO}	—	0.1 × V_{CCIO}	0.9 × V_{CCIO}	1.5	-0.5

Table 1–24 lists the single-ended SSTL and HSTL I/O reference voltage specifications for Arria II GX devices.

Table 1–24. Single-Ended SSTL and HSTL I/O Reference Voltage Specifications for Arria II GX Devices

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}	V_{REF} - 0.04	V_{REF}	V_{REF} + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V_{REF} - 0.04	V_{REF}	V_{REF} + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.47 × V_{CCIO}	0.5 × V_{CCIO}	0.53 × V_{CCIO}	0.47 × V_{CCIO}	0.5 × V_{CCIO}	0.53 × V_{CCIO}
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	0.85	0.9	0.95
HSTL-15 Class I, II	1.425	1.5	1.575	0.71	0.75	0.79	0.71	0.75	0.79
HSTL-12 Class I, II	1.14	1.2	1.26	0.48 × V_{CCIO}	0.5 × V_{CCIO}	0.52 × V_{CCIO}	—	V_{CCIO}/2	—

Table 1–25 lists the single-ended SSTL and HSTL I/O reference voltage specifications for Arria II GZ devices.

Table 1–25. Single-Ended SSTL and HSTL I/O Reference Voltage Specifications for Arria II GZ Devices

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}	V_{REF} - 0.04	V_{REF}	V_{REF} + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V_{REF} - 0.04	V_{REF}	V_{REF} + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.47 × V_{CCIO}	0.5 × V_{CCIO}	0.53 × V_{CCIO}	0.47 × V_{CCIO}	V_{REF}	0.53 × V_{CCIO}
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	V_{CCIO}/2	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	V_{CCIO}/2	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 × V_{CCIO}	0.5 × V_{CCIO}	0.53 × V_{CCIO}	—	V_{CCIO}/2	—

Table 1–33 lists the differential I/O standard specifications for Arria II GZ devices.

Table 1–33. Differential I/O Standard Specifications for Arria II GZ Devices *(Note 1)*

I/O Standard *(2)*	V_{CCIO} (V)			V_{ID} (mV)			$V_{ICM(DC)}$ (V)		V_{OD} (V) *(3)*			V_{OCM} (V) *(3)*		
	Min	Typ	Max	Min	Cond.	Max	Min	Max	Min	Typ	Max	Min	Typ	Max
2.5 V LVDS (HIO)	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.05	1.8	0.247	—	0.6	1.125	1.25	1.375
2.5 V LVDS (VIO)	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.05	1.8	0.247	—	0.6	1	1.25	1.5
RSDS (HIO)	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.3	1.4	0.1	0.2	0.6	0.5	1.2	1.4
RSDS (VIO)	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.3	1.4	0.1	0.2	0.6	0.5	1.2	1.5
Mini-LVDS (HIO)	2.375	2.5	2.625	200	—	600	0.4	1.325	0.25	—	0.6	1	1.2	1.4
Mini-LVDS (VIO)	2.375	2.5	2.625	200	—	600	0.4	1.325	0.25	—	0.6	1	1.2	1.5
LVPECL	2.375	2.5	2.625	300	—	—	0.6	1.8	—	—	—	—	—	—
BLVDS *(4)*	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—

Notes to Table 1–33:

(1) 1.4-V/1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 1–21.
(2) Vertical I/O (VIO) is top and bottom I/Os; horizontal I/O (HIO) is left and right I/Os.
(3) R_L range: $90 \leq RL \leq 110\ \Omega$.
(4) There are no fixed V_{ICM}, V_{OD}, and V_{OCM} specifications for BLVDS. These specifications depend on the system topology.

Power Consumption for the Arria II Device Family

Altera offers two ways to estimate power for a design:

- Using the Microsoft Excel-based Early Power Estimator
- Using the Quartus® II PowerPlay Power Analyzer feature

The interactive Microsoft Excel-based Early Power Estimator is typically used prior to designing the FPGA in order to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after place-and-route is complete. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities which, when combined with detailed circuit models, can yield very accurate power estimates.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in volume 3 of the *Quartus II Handbook*.

Table 1–34. Transceiver Specifications for Arria II GX Devices *(Note 1)* (Part 5 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
LTD lock time *(11)*	—	0	100	4000	0	100	4000	0	100	4000	0	100	4000	ns
Data lock time from `rx_freqlocked` *(12)*	—	—	—	4000	—	—	4000	—	—	4000	—	—	4000	ns
Programmable DC gain	DC Gain Setting = 0	—	0	—	—	0	—	—	0	—	—	0	—	dB
	DC Gain Setting = 1	—	3	—	—	3	—	—	3	—	—	3	—	dB
	DC Gain Setting = 2	—	6	—	—	6	—	—	6	—	—	6	—	dB
Transmitter														
Supported I/O Standards	1.5-V PCML													
Data rate	—	600	—	6375	600	—	3750	600	—	3750	600	—	3125	Mbps
V_{OCM}	0.65 V setting	—	650	—	—	650	—	—	650	—	—	650	—	mV
Differential on-chip termination resistors	100–Ω setting	—	100	—	—	100	—	—	100	—	—	100	—	Ω
Return loss differential mode	PCIe	50 MHz to 1.25 GHz: –10dB												
	XAUI	312 MHz to 625 MHz: –10dB 625 MHz to 3.125 GHz: –10dB/decade slope												
Return loss common mode	PCIe	50 MHz to 1.25 GHz: –6dB												
Rise time *(2)*	—	50	—	200	50	—	200	50	—	200	50	—	200	ps
Fall time	—	50	—	200	50	—	200	50	—	200	50	—	200	ps

Table 1–34. Transceiver Specifications for Arria II GX Devices *(Note 1)* (Part 7 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Digital reset pulse width	—	Minimum is 2 parallel clock cycles												

Notes to Table 1–34:

(1) For AC-coupled links, the on-chip biasing circuit is switched off before and during configuration. Ensure that input specifications are not violated during this period.

(2) The rise/fall time is specified from 20% to 80%.

(3) To calculate the REFCLK rms phase jitter requirement at reference clock frequencies other than 100 MHz, use the following formula:
REFCLK rms phase jitter at f (MHz) = REFCLK rms phase jitter at 100 MHz * 100/f.

(4) The minimum `reconfig_clk` frequency is 2.5 MHz if the transceiver channel is configured in **Transmitter only** mode. The minimum `reconfig_clk` frequency is 37.5 MHz if the transceiver channel is configured in **Receiver only** or **Receiver and Transmitter** mode. For more information, refer to *AN 558: Implementing Dynamic Reconfiguration in Arria II Devices*.

(5) If your design uses more than one dynamic reconfiguration controller instances (`altgx_reconfig`) to control the transceiver channels (`altgx`) physically located on the same side of the device, and if you use different `reconfig_clk` sources for these `altgx_reconfig` instances, the delta time between any two of these `reconfig_clk` sources becoming stable must not exceed the maximum specification listed.

(6) The device cannot tolerate prolonged operation at this absolute maximum.

(7) You must use the 1.1-V RX V_{ICM} setting if the input serial data standard is LVDS and the link is DC-coupled.

(8) The rate matcher supports only up to ±300 parts per million (ppm).

(9) Time taken to `rx_pll_locked` goes high from `rx_analogreset` de-assertion. Refer to Figure 1–1.

(10) The time in which the CDR must be kept in lock-to-reference mode after `rx_pll_locked` goes high and before `rx_locktodata` is asserted in manual mode. Refer to Figure 1–1.

(11) The time taken to recover valid data after the `rx_locktodata` signal is asserted in manual mode. Refer to Figure 1–1.

(12) The time taken to recover valid data after the `rx_freqlocked` signal goes high in automatic mode. Refer to Figure 1–2.

(13) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

Figure 1–1 shows the lock time parameters in manual mode.

LTD = lock-to-data. LTR = lock-to-reference.

Figure 1–1. Lock Time Parameters for Manual Mode

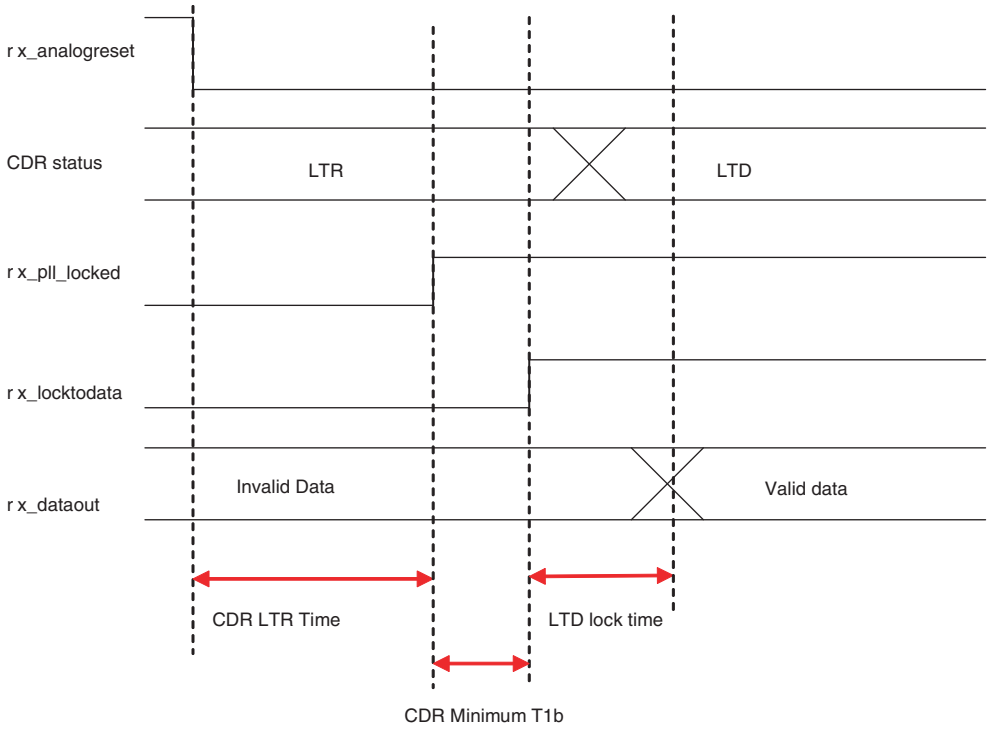


Figure 1–2 shows the lock time parameters in automatic mode.

Figure 1–2. Lock Time Parameters for Automatic Mode

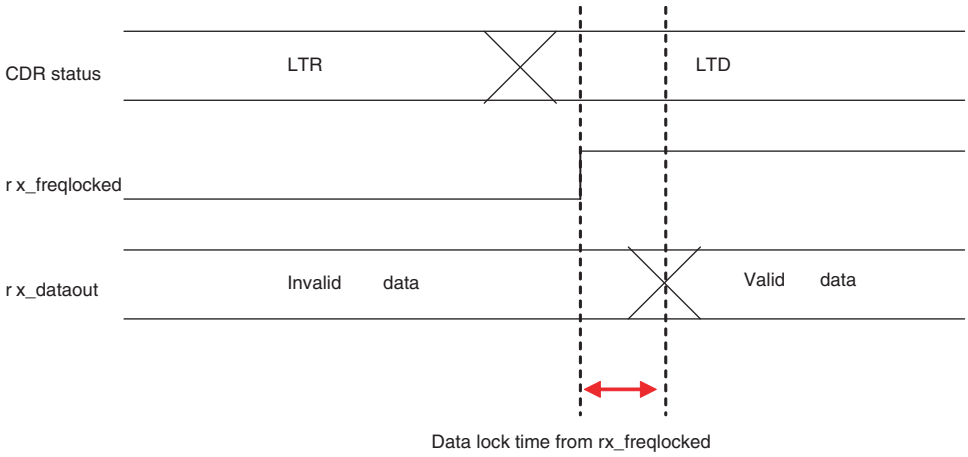


Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices *(Note 1)* (Part 2 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Jitter tolerance at 2488.32 Mbps	Jitter frequency = 0.06 KHz Pattern = PRBS15		> 15			> 15			> 15			> 15		UI
	Jitter frequency = 100 KHZ Pattern = PRBS15		> 1.5			> 1.5			> 1.5			> 1.5		UI
	Jitter frequency = 1 MHz Pattern = PRBS15		> 0.15			> 0.15			> 0.15			> 0.15		UI
	Jitter frequency = 10 MHz Pattern = PRBS15		> 0.15			> 0.15			> 0.15			> 0.15		UI
XAUI Transmit Jitter Generation *(3)*														
Total jitter at 3.125 Gbps	Pattern = CJPAT	—	—	0.3	—	—	0.3	—	—	0.3	—	—	0.3	UI
Deterministic jitter at 3.125 Gbps	Pattern = CJPAT	—	—	0.17	—	—	0.17	—	—	0.17	—	—	0.17	UI
XAUI Receiver Jitter Tolerance *(3)*														
Total jitter	—		> 0.65			> 0.65			> 0.65			> 0.65		UI
Deterministic jitter	—		> 0.37			> 0.37			> 0.37			> 0.37		UI
Peak-to-peak jitter	Jitter frequency = 22.1 KHz		> 8.5			> 8.5			> 8.5			> 8.5		UI
Peak-to-peak jitter	Jitter frequency = 1.875 MHz		> 0.1			> 0.1			> 0.1			> 0.1		UI
Peak-to-peak jitter	Jitter frequency = 20 MHz		> 0.1			> 0.1			> 0.1			> 0.1		UI
PCIe Transmit Jitter Generation *(4)*														
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	—	—	0.25	—	—	0.25	—	—	0.25	—	—	0.25	UI

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices *(Note 1)* (Part 7 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
SSC modulation deviation at 1.5 Gbps (G1)	Compliance pattern		5700			5700			5700			5700		ppm
RX differential skew at 1.5 Gbps (G1)	Compliance pattern		80			80			80			80		ps
RX AC common mode voltage at 1.5 Gbps (G1)	Compliance pattern		150			150			150			150		mV
Total jitter tolerance at 3.0 Gbps (G2)	Compliance pattern		> 0.65			> 0.65			> 0.65			> 0.65		UI
Deterministic jitter tolerance at 3.0 Gbps (G2)	Compliance pattern		> 0.35			> 0.35			> 0.35			> 0.35		UI
SSC modulation frequency at 3.0 Gbps (G2)	Compliance pattern		33			33			33			33		kHz
SSC modulation deviation at 3.0 Gbps (G2)	Compliance pattern		5700			5700			5700			5700		ppm
RX differential skew at 3.0 Gbps (G2)	Compliance pattern		75			75			75			75		ps
RX AC common mode voltage at 3.0 Gbps (G2)	Compliance pattern		150			150			150			150		mV
Total jitter tolerance at 6.0 Gbps (G3)	Compliance pattern		> 0.60			> 0.60			> 0.60			> 0.60		UI
Random jitter tolerance at 6.0 Gbps (G3)	Compliance pattern		> 0.18			> 0.18			> 0.18			> 0.18		UI
SSC modulation frequency at 6.0 Gbps (G3)	Compliance pattern		33			33			33			33		kHz
SSC modulation deviation at 6.0 Gbps (G3)	Compliance pattern		5700			5700			5700			5700		ppm
RX differential skew at 6.0 Gbps (G3)	Compliance pattern		30			30			30			30		ps
RX AC common mode voltage at 6.0 Gbps (G3)	Compliance pattern		100			100			100			100		mV

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices *(Note 1)* (Part 10 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Sinusoidal jitter tolerance at 3072 Mbps	Jitter frequency = 21.8 KHz Pattern = CJPAT		> 8.5			> 8.5			> 8.5			> 8.5		UI
	Jitter frequency = 1843.2 KHz to 20 MHz Pattern = CJPAT		> 0.1			> 0.1			> 0.1			> 0.1		UI

Notes to Table 1–40:

(1) Dedicated `refclk` pins are used to drive the input reference clocks. The jitter numbers are valid for the stated conditions only.
(2) The jitter numbers for SONET/SDH are compliant to the GR-253-CORE Issue 3 Specification.
(3) The jitter numbers for XAUI are compliant to the IEEE802.3ae-2002 Specification.
(4) The jitter numbers for PCIe are compliant to the PCIe Base Specification 2.0.
(5) The jitter numbers for SRIO are compliant to the RapidIO Specification 1.3.
(6) The jitter numbers for GIGE are compliant to the IEEE802.3-2002 Specification.
(7) The jitter numbers for HiGig are compliant to the IEEE802.3ae-2002 Specification.
(8) The HD-SDI and 3G-SDI jitter numbers are compliant to the SMPTE292M and SMPTE424M Specifications.
(9) Arria II PCIe receivers are compliant to this specification provided the VTX_CM-DC-ACTIVEIDLE-DELTA of the upstream transmitter is less than 50 mV.
(10) The jitter numbers for Serial Advanced Technology Attachment (SATA) are compliant to the Serial ATA Revision 3.0 Specification.
(11) The jitter numbers for Common Public Radio Interface (CPRI) are compliant to the CPRI Specification V3.0.
(12) The jitter numbers for Open Base Station Architecture Initiative (OBSAI) are compliant to the OBSAI RP3 Specification V4.1.

Table 1–41 lists the transceiver jitter specifications for all supported protocols for Arria II GZ devices.

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices *(Note 1)*, *(2)* (Part 1 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
SONET/SDH Transmit Jitter Generation *(3)*								
Peak-to-peak jitter at 622.08 Mbps	Pattern = PRBS15	—	—	0.1	—	—	0.1	UI
RMS jitter at 622.08 Mbps	Pattern = PRBS15	—	—	0.01	—	—	0.01	UI
Peak-to-peak jitter at 2488.32 Mbps	Pattern = PRBS15	—	—	0.1	—	—	0.1	UI
RMS jitter at 2488.32 Mbps	Pattern = PRBS15	—	—	0.01	—	—	0.01	UI
SONET/SDH Receiver Jitter Tolerance *(3)*								
Jitter tolerance at 622.08 Mbps	Jitter frequency = 0.03 KHz Pattern = PRBS15		> 15			> 15		UI
	Jitter frequency = 25 KHZ Pattern = PRBS15		> 1.5			> 1.5		UI
	Jitter frequency = 250 KHz Pattern = PRBS15		> 0.15			> 0.15		UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices *(Note 1)*, *(2)* (Part 6 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Deterministic jitter at 3.0 Gbps (G2)	Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Total jitter at 6.0 Gbps (G3)	Pattern = CJPAT	—	—	0.25	—	—	0.25	UI
Random jitter at 6.0 Gbps (G3)	Pattern = CJPAT	—	—	0.15	—	—	0.15	UI
SAS Receiver Jitter Tolerance *(13)*								
Total jitter tolerance at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.65	—	—	0.65	UI
Deterministic jitter tolerance at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Sinusoidal jitter tolerance at 1.5 Gbps (G1)	Jitter frequency = 900 KHz to 5 MHz Pattern = CJTPAT BER = 1E-12	> 0.1			> 0.1			UI
CPRI Transmit Jitter Generation *(14)*								
Total jitter	E.6.HV, E.12.HV Pattern = CJPAT	—	—	0.279	—	—	0.279	UI
	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Deterministic jitter	E.6.HV, E.12.HV Pattern = CJPAT	—	—	0.14	—	—	0.14	UI
	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	—	—	0.17	—	—	0.17	UI
CPRI Receiver Jitter Tolerance *(14)*								
Total jitter tolerance	E.6.HV, E.12.HV Pattern = CJPAT	> 0.66			> 0.66			UI
Deterministic jitter tolerance	E.6.HV, E.12.HV Pattern = CJPAT	> 0.4			> 0.4			UI
Total jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	> 0.65			> 0.65			UI
Deterministic jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	> 0.37			> 0.37			UI
Combined deterministic and random jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJPAT	> 0.55			> 0.55			UI
OBSAI Transmit Jitter Generation *(15)*								
Total jitter at 768 Mbps, 1536 Mbps, and 3072 Mbps	REFCLK = 153.6 MHz Pattern CJPAT	—	—	0.35	—	—	0.35	UI
Deterministic jitter at 768 MBps, 1536 Mbps, and 3072 Mbps	REFCLK = 153.6 MHz Pattern CJPAT	—	—	0.17	—	—	0.17	UI

Table 1–47. DSP Block Performance Specifications for Arria II GZ Devices *(Note 1)* (Part 2 of 2)

Mode	Resources Used	Performance		Unit
	Number of Multipliers	–3	–4	
Double mode	1	440	380	MHz

Notes to Table 1–47:

(1) Maximum is for fully pipelined block with **Round** and **Saturation** disabled.

(2) Maximum for loopback input registers disabled, **Round** and **Saturation** disabled, and pipeline and output registers enabled.

Embedded Memory Block Specifications

Table 1–48 lists the embedded memory block specifications for Arria II GX devices.

Table 1–48. Embedded Memory Block Performance Specifications for Arria II GX Devices

Memory	Mode	Resources Used		Performance				Unit
		ALUTs	Embedded Memory	I3	C4	C5,I5	C6	
Memory Logic Array Block (MLAB)	Single port 64 × 10	0	1	450	500	450	378	MHz
	Simple dual-port 32 × 20 single clock	0	1	270	500	450	378	MHz
	Simple dual-port 64 × 10 single clock	0	1	428	500	450	378	MHz
M9K Block	Single-port 256 × 36	0	1	360	400	360	310	MHz
	Single-port 256 × 36, with the **read-during-write** option set to **Old Data**	0	1	250	280	250	210	MHz
	Simple dual-port 256 × 36 single CLK	0	1	360	400	360	310	MHz
	Single-port 256 × 36 single CLK, with the **read-during-write** option set to **Old Data**	0	1	250	280	250	210	MHz
	True dual port 512 × 18 single CLK	0	1	360	400	360	310	MHz
	True dual-port 512 × 18 single CLK, with the **read-during-write** option set to **Old Data**	0	1	250	280	250	210	MHz
	Min Pulse Width (clock high time)	—	—	900	850	950	1130	ps
	Min Pulse Width (clock low time)	—	—	730	690	770	920	ps

Configuration

Table 1–50 lists the configuration mode specifications for Arria II GX and GZ devices.

Table 1–50. Configuration Mode Specifications for Arria II Devices

Programming Mode	DCLK Frequency			Unit
	Min	Typ	Max	
Passive serial	—	—	125	MHz
Fast passive parallel	—	—	125	MHz
Fast active serial (fast clock)	17	26	40	MHz
Fast active serial (slow clock)	8.5	13	20	MHz
Remote update only in fast AS mode	—	—	10	MHz

JTAG Specifications

Table 1–51 lists the JTAG timing parameters and values for Arria II GX and GZ devices.

Table 1–51. JTAG Timing Parameters and Values for Arria II Devices

Symbol	Description	Min	Max	Unit
t_{JCP}	TCK clock period	30	—	ns
t_{JCH}	TCK clock high time	14	—	ns
t_{JCL}	TCK clock low time	14	—	ns
$t_{JPSU\ (TDI)}$	TDI JTAG port setup time	1	—	ns
$t_{JPSU\ (TMS)}$	TMS JTAG port setup time	3	—	ns
t_{JPH}	JTAG port hold time	5	—	ns
t_{JPCO}	JTAG port clock to output	—	11	ns
t_{JPZX}	JTAG port high impedance to valid output	—	14	ns
t_{JPXZ}	JTAG port valid output to high impedance	—	14	ns

Chip-Wide Reset (Dev_CLRn) Specifications

Table 1–52 lists the specifications for the chip-wide reset (Dev_CLRn) for Arria II GX and GZ devices.

Table 1–52. Chip-Wide Reset (Dev_CLRn) Specifications for Arria II Devices

Description	Min	Typ	Max	Unit
Dev_CLRn	500	—	—	µs

Table 1–54. High-Speed I/O Specifications for Arria II GZ Devices *(Note 1), (2), (10)* (Part 3 of 3)

Symbol	Conditions	C3, I3			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
t_{RISE} & t_{FALL}	True differential I/O standards	—	—	200	—	—	200	ps
	Emulated differential I/O standards with three external output resistor networks	—	—	250	—	—	300	ps
	Emulated differential I/O standards with one external output resistor	—	—	500	—	—	500	ps
TCCS	True LVDS	—	—	100	—	—	100	ps
	Emulated LVDS_E_3R	—	—	250	—	—	250	ps
Receiver								
True differential I/O standards - $f_{HSDRDPA}$ (data rate)	SERDES factor J = 3 to 10	150	—	1250	150	—	1250	Mbps
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	*(4)*	—	*(6)*	*(4)*	—	*(6)*	Mbps
	SERDES factor J = 2, uses DDR registers	*(4)*	—	*(5)*	*(4)*	—	*(5)*	Mbps
	SERDES factor J = 1, uses an SDR register	*(4)*	—	*(5)*	*(4)*	—	*(5)*	Mbps
DPA run length	DPA mode	—	—	10000	—	—	10000	UI
Soft-CDR PPM tolerance	Soft-CDR mode	—	—	300	—	—	300	± PPM
Sampling Window (SW)	Non-DPA mode	—	—	300	—	—	300	ps

Notes to Table 1–54:

(1) When J = 3 to 10, use the SERDES block.

(2) When J = 1 or 2, bypass the SERDES block.

(3) Clock Boost Factor (W) is the ratio between input data rate to the input clock rate.

(4) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.

(5) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.

(6) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and the receiver sampling margin to determine the maximum data rate supported.

(7) This is achieved by using the LVDS and DPA clock network.

(8) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.

(9) This only applies to DPA and soft-CDR modes.

(10) This only applies to LVDS source synchronous mode.

Table 1–55 lists DPA lock time specifications for Arria II GX and GZ devices.

Glossary

Table 1–68 lists the glossary for this chapter.

Table 1–68. Glossary (Part 1 of 4)

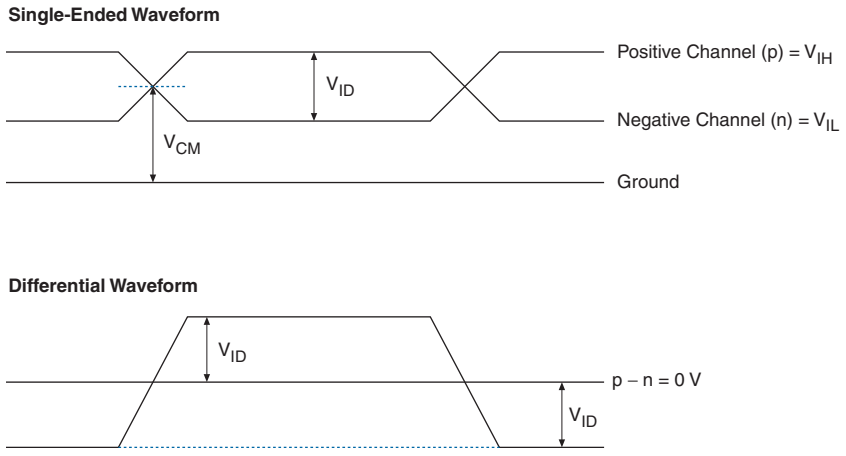
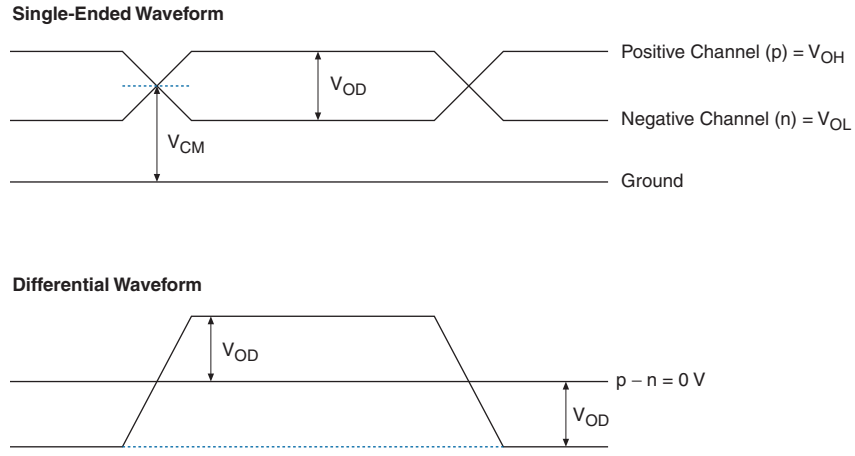
Letter	Subject	Definitions
A, B, C, D	Differential I/O Standards	*Receiver Input Waveforms*  *Transmitter Output Waveforms* 
E, F	f_{HSCLK}	Left/Right PLL input clock frequency.
	f_{HSDR}	High-speed I/O block: Maximum/minimum LVDS data transfer rate (f_{HSDR} = 1/TUI), non-DPA.
	$f_{HSDRDPA}$	High-speed I/O block: Maximum/minimum LVDS data transfer rate ($f_{HSDRDPA}$ = 1/TUI), DPA.

Table 1–68. Glossary (Part 2 of 4)

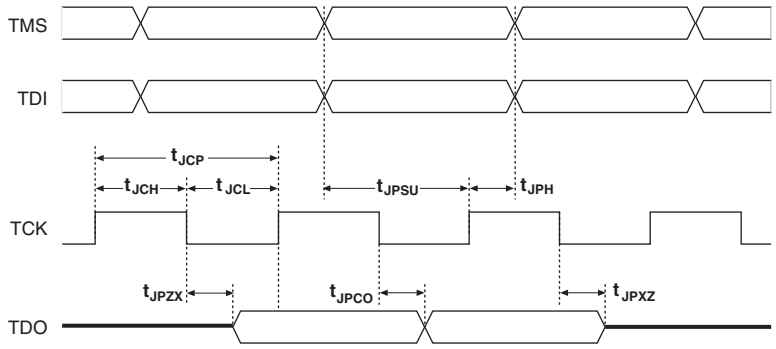
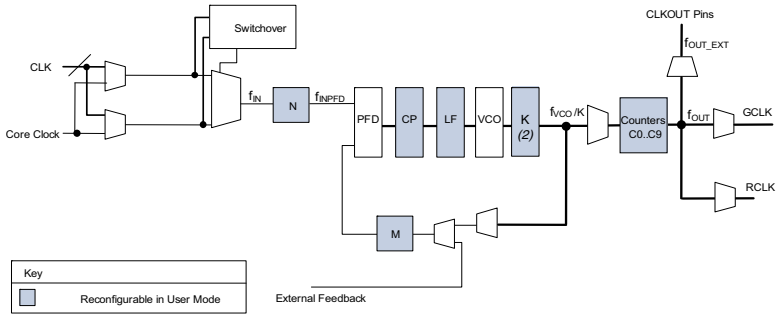
Letter	Subject	Definitions
G, H, I, J	J	High-speed I/O block: Deserialization factor (width of parallel data bus).
	JTAG Timing Specifications	JTAG Timing Specifications: 
K, L, M, N, O, P	PLL Specifications	PLL Specification parameters: **Diagram of PLL Specifications** ***(1)***  **Notes:** (1) CoreClock can only be fed by dedicated clock input pins or PLL outputs. (2) This is the VCO post-scale counter K.
Q, R	R_L	Receiver differential input discrete resistor (external to the Arria II device).

Table 1–68. Glossary (Part 4 of 4)

Letter	Subject	Definitions
U, V	$V_{CM(DC)}$	DC common mode input voltage.
	V_{ICM}	Input common mode voltage: The common mode of the differential signal at the receiver.
	V_{ID}	Input differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	$V_{DIF(AC)}$	AC differential input voltage: Minimum AC input differential voltage required for switching.
	$V_{DIF(DC)}$	DC differential input voltage: Minimum DC input differential voltage required for switching.
	V_{IH}	Voltage input high: The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	$V_{IH(AC)}$	High-level AC input voltage.
	$V_{IH(DC)}$	High-level DC input voltage.
	V_{IL}	Voltage input low: The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	$V_{IL(AC)}$	Low-level AC input voltage.
	$V_{IL(DC)}$	Low-level DC input voltage.
	V_{OCM}	Output common mode voltage: The common mode of the differential signal at the transmitter.
	V_{OD}	Output differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
W, X, Y, Z	W	High-speed I/O block: The clock boost factor.

Document Revision History

Table 1–69 lists the revision history for this chapter.

Table 1–69. Document Revision History (Part 1 of 2)

Date	Version	Changes
December 2013	4.4	Updated Table 1–34 and Table 1–35.
July 2012	4.3	■ Updated the $V_{CCH\_GXBL/R}$ operating conditions in Table 1–6. ■ Finalized Arria II GZ information in Table 1–20. ■ Added BLVDS specification in Table 1–32 and Table 1–33. ■ Updated input and output waveforms in Table 1–68.
December 2011	4.2	■ Updated Table 1–32, Table 1–33, Table 1–34, Table 1–35, Table 1–40, Table 1–41, Table 1–54, and Table 1–67. ■ Minor text edits.
June 2011	4.1	■ Added Table 1–60. ■ Updated Table 1–32, Table 1–33, Table 1–38, Table 1–41, and Table 1–61. ■ Updated the “Switching Characteristics” section introduction. ■ Minor text edits.